

Cross section TEM sample preparation unit

- **Ultrasonic cutter:**
Variable frequency cutter, used to cut the rectangular (4x3mm) and circular (2.3mm and 3mm in dia.) pieces of Si/Ge/GaAs samples. It is from GATAN.
- **Dimple Grinder:**
Used to create a dimple after disc grinding in the cross section samples. It is from GATAN.
- **Precision Ion Polishing System (PIPS):**
used for the final thinning of the sample. It is from GATAN.

It has following features :

- Beam energy from 0KeV to 6KeV
- Beam angle ± 100 , sample can be milled from both sides (top and bottom)
- It also has a cold stage where temperature of the sample stage can be controlled to liquid N₂ temperature. PIPS

